

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4	("6206760" "6402598" "6405399" "6595831").PN.	US-PGPUB; USPAT	OR	ON	2006/11/30 13:47
S1	225	sato-shuzo.in. yasuda-zenya.in. komai-naoki.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 17:46
S2	3534	205/640-686.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 17:48
S3	10	S1 and S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 10:55
S4	307866	sony.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 17:54
S5	11	S4 and S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 17:54
S6	8	S5 not S3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 17:56
S7	308349	centripetal centrifugal	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 17:57

## EAST Search History

S8	79	S7 and S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 17:58
S9	452	(drop dropp\$3 place plac\$3 deliver deliver\$3 dispose disposed apply applying applicat\$3 discharg\$3 flow flow\$3) with (electrolyte slurry "electropolishing fluid") with (center middle inner) with (workpiece work substrate microelectronic wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 11:05
S10	452	(drop dropp\$3 place plac\$3 deliver deliver\$3 dispose disposed apply applying applicat\$3 discharg\$3 (flow not (flow adj rate)) flow\$3) with (electrolyte slurry "electropolishing fluid") with (center middle inner) with (workpiece work substrate microelectronic wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 11:01
S11	149	((drop dropp\$3 place plac\$3 deliver deliver\$3 dispose disposed apply applying applicat\$3 discharg\$3 flow flow\$3) with (electrolyte slurry "electropolishing fluid") with (center middle inner) with (pad)) and (workpiece work substrate microelectronic wafer) and (CMP (chemical adj mechanical polishing) electropolishing electropolish)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 11:06
S12	66	((drop dropp\$3 place plac\$3 deliver deliver\$3 dispose disposed apply applying applicat\$3 discharg\$3 flow flow\$3) with (electrolyte slurry "electropolishing fluid") with ((center middle inner) near2 (pad))) and (workpiece work substrate microelectronic wafer) and (CMP (chemical adj mechanical polishing) electropolishing electropolish)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:01

## EAST Search History

S13	18	(US-20040149592-\$ or US-20020088709-\$ or US-20030141201-\$ or US-20030121797-\$ or US-20050124267-\$ or US-20050113006-\$ or US-20040242126-\$ or US-20050037936-\$ or US-20040116313-\$ or US-20040087257-\$).did. or (US-6582578-\$ or US-6551488-\$ or US-6899609-\$ or US-6461230-\$ or US-6409577-\$ or US-6238270-\$ or US-5879226-\$ or US-5866480-\$). did.	US-PGPUB; USPAT	OR	ON	2006/09/06 11:49
S14	0	S13 and ((recycle cup collect) with (electrolyte slurry "polishing fluid"))	US-PGPUB; USPAT	OR	ON	2006/09/06 11:50
S15	18	(US-20040149592-\$ or US-20020088709-\$ or US-20030141201-\$ or US-20030121797-\$ or US-20050124267-\$ or US-20050113006-\$ or US-20040242126-\$ or US-20050037936-\$ or US-20040116313-\$ or US-20040087257-\$).did. or (US-6582578-\$ or US-6551488-\$ or US-6899609-\$ or US-6461230-\$ or US-6409577-\$ or US-6238270-\$ or US-5879226-\$ or US-5866480-\$). did.	US-PGPUB; USPAT	OR	ON	2006/09/06 11:57
S16	6	S15 and (cathode anode electrode)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 11:57
S17	4	((drop dropp\$3 place plac\$3 deliver deliver\$3 dispose disposed apply applying applicat\$3 discharg\$3 flow flow\$3) with (electrolyte slurry "electropolishing fluid") with ((center middle inner) near2 (pad))) and (workpiece work substrate microelectronic wafer) and (EMP (electomechanical adj polishing) electropolishing electropolish)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:05

## EAST Search History

S18	3534	205/640-686.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:05
S19	522	S18 and (ECMP (electrochemical adj mechanical adj polishing) electropolishing electropolish)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:06
S20	138	S18 and (ECMP (electrochemical adj mechanical adj polishing) electropolishing electropolish) and pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:08
S21	8	S18 and (ECMP (electrochemical adj mechanical adj polishing) electropolishing electropolish) and (pad near2 (center middle))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:07
S22	213	(ECMP CMP (chemical adj mechanical adj (polish polish\$3 planariz\$3 etch etch\$3)) (electrochemical adj mechanical adj (polish polish\$3 planariz\$3 etch etch\$3))) and ((slurry solution electrolyte) same (((abrasive adj grains) alumina)) with (control specifying specif\$3 controll\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 16:57
S23	0	(ECMP (electrochemical adj mechanical adj (polish polish\$3 planariz\$3 etch etch\$3))) and ((slurry solution electrolyte) same (((abrasive adj grains) alumina)) with (control specifying specif\$3 controll\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 16:56
S24	213	(CMP (chemical adj mechanical adj (polish polish\$3 planariz\$3 etch etch\$3))) and ((slurry solution electrolyte) same (((abrasive adj grains) alumina)) with (control specifying specif\$3 controll\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 16:58

## EAST Search History

S25	213	(CMP (chemical adj mechanical adj (polish polish\$3 planariz\$3 etch etch\$3))) and ((slurry solution electrolyte) same (((abrasive adj grains) alumina) with (control specifying specif\$3 controll\$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 17:00
S26	159	(CMP (chemical adj mechanical adj (polish polish\$3 planariz\$3 etch etch\$3))) and ((slurry solution electrolyte) same ((alumina) with (control specifying specif\$3 controll\$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 16:59
S27	23	(US-20040149592-\$ or US-20030141201-\$ or US-20030121797-\$ or US-20020088709-\$ or US-20030116446-\$ or US-20050124267-\$ or US-20050113006-\$ or US-20050037936-\$ or US-20040242126-\$ or US-20040116313-\$ or US-20040087257-\$ or US-20050145507-\$).did. or (US-6551488-\$ or US-6582578-\$ or US-5866480-\$ or US-6899609-\$ or US-6461230-\$ or US-6409577-\$ or US-6238270-\$ or US-5879226-\$ or US-6464855-\$ or US-5911619-\$ or US-5807165-\$).did.	US-PGPUB; USPAT	OR	ON	2006/11/29 17:00
S28	1	S27 and S25	US-PGPUB; USPAT	OR	ON	2006/11/29 17:00
S29	144	(CMP (chemical adj mechanical adj (polish polish\$3 planariz\$3 etch etch\$3))) and ((slurry solution electrolyte) with (((abrasive adj grains) alumina) with (control specifying specif\$3 controll\$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 17:08
S30	1	(CMP (chemical adj mechanical adj (polish polish\$3 planariz\$3 etch etch\$3))) and (nozzle same (slurry solution electrolyte) with (((abrasive adj grains) alumina) with (control specifying specif\$3 controll\$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 17:03
S31	10	(CMP (chemical adj mechanical adj (polish polish\$3 planariz\$3 etch etch\$3))) and ( (slurry solution electrolyte) with (((abrasive adj grains) alumina) with (control specifying specif\$3 controll\$3))) and (nozzle with (slurry alumina (abrasive adj grain)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 17:04

## EAST Search History

S32	7	(CMP (chemical adj mechanical adj (polish polish\$3 planariz\$3 etch etch\$3))) and ((slurry solution electrolyte) with (((abrasive adj grains) alumina) with (control specifying specif\$3 controll\$3) with amount))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 17:21
S33	7	S32 not S31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 17:09
S34	13	("2003/0116446").URPN.	USPAT	OR	ON	2006/11/29 17:20

## EAST Search History

S35	146	("20010016469"   "20010024878"   "20010036746"   "20010042690"   "20020008036"   "20020016064"   "20020016073"   "20020016272"   "20020040100"   "20020070126"   "20020072309"   "20020074230"   "20020088709"   "20020096659"   "20020108861"   "20020130049"   "20020139055"   "20020160698"   "20030073385"   "20030079416"   "20030083214"   "20030104762"   "20030113996"   "20030114004"   "20030116445"   "20030116446"   "20030136055"   "20030153184"   "20030170091"   "2582020"   "3239441"   "3873512"   "4263113"   "4663005"   "4666683"   "4793895"   "4934102"   "4992135"   "5002645"   "5096550"   "5114548"   "5129981"   "5209816"   "5217586"   "5225034"   "5256565"   "5340370"   "5391258"   "5407526"   "5534106"   "5543032"   "5567300"   "5575706"   "5770095"   "5783489"   "5800577"   "5807165"   "5846882"   "5866031"   "5880003"   "5897375"   "5911619"   "5954997"   "5965036"   "6001730"   "6004880"   "6056864"   "6063306"   "6066030"   "6068879"   "6077412"   "6083840"   "6090239"   "6096652"   "6099604"   "6103096"   "6106728"   "6117775"   "6117783"   "6117853"   "6121152"   "6126853"   "6139763"   "6143155"   "6143656"   "6153043"   "6171352"   "6176992"   "6177026"   "6190237"   "6194317"   "6206756"   "6217416"   "6218305"   "6234870"   "6238592"   "6248222"   "6258711"   "6258721"   "6273786"   "6276996"   "6280598"   "6299741"   "6303049"   "6303551"   "6310019"   "6315803"   "6315883"   "6348076"   "6354916"   "6355075"   "6355153"   "6375693"   "6379223"   "6391166"   ("6395152"   "6416685"   "6419554"   "6428721"   "6429133"   "6440186"   "6440295"   "6447371"   "6454819"   "6455479"   "6508952"   "6551935"   "6555158"   "6562719"   "6565619"   "6569349"   "6579153"   "6592742"   "6593239"   "6596638"   "6602112"   "6605537"   "6616976"   "6620215"   "6653242"	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/29 17:21
-----	-----	---	------------------------------	----	----	------------------

## EAST Search History

S36	6	S35 and (substrate adj support)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 18:01
S37	2	"5807165".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 18:01